

Title (en)

MICRO-ALLOYED OXYGEN-FREE COPPER ALLOY AND ITS USE

Title (de)

MIKROLEGIERTE SAUERSTOFFFREIE KUPFERLEGIERUNG UND IHRE VERWENDUNG

Title (fr)

ALLIAGE DE CUIVRE EXEMPT D'OXYGENE MICROALLIE ET UTILISATION DE CELUI-CI

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Application

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Abstract (en)

[origin: WO02072901A1] An oxygen-free copper alloy comprising oxygen-free copper and, micro-alloyed therein, about 1 250 ppm tin (Sn) and/or about 1 150 ppm manganese (Mn). The invention also relates to the use of said copper alloy.

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